

Gunter Semiconductor GmbH

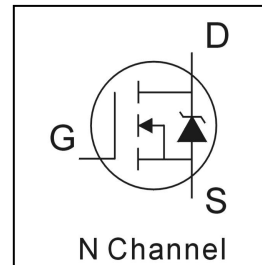
GFC230

N Channel Power MOSFET with low RDS(on)

Chip Specification

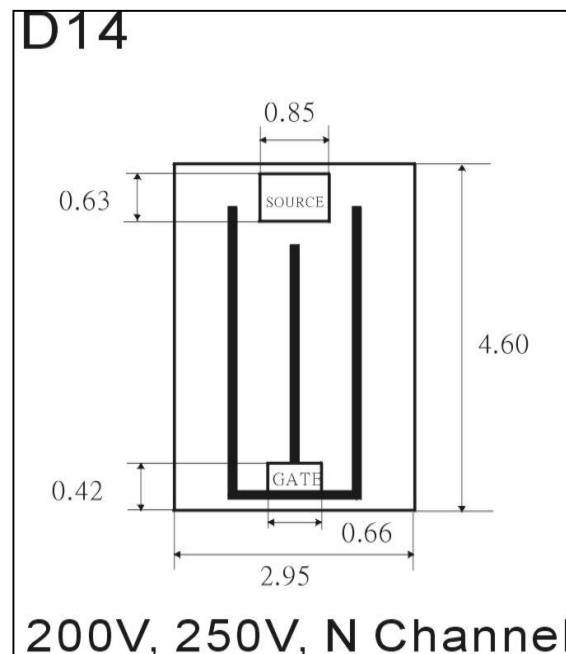
General Description:

- * Advanced Process Technology
- * Dynamic dV/dt Rating
- * **150°C Operating Temperature**
- * **Fast Switching**
- * **Fully Avalanche Rated**
- * **Low RDS(on)**



Mechanical Data:

D14
Dimension 2.95mm x 4.60mm
Thickness: 400 μm
Metallization:
Top : : Al
Backside : CrNiAg / Au
Suggested Bonding Conditions:
Die Mounting: Solder Perform
95/5 PbSn or 92.5/2.5/5 PbAgIn
Source Bonding Wire: 8 mil Al



Absolute Maximum Rating

@Ta=25°C

Characteristics	Symbol	Limit	Unit	Test Conditions
Drain-to-Source Breakdown Voltage	V(BR)DSS	200	V	VGS=0V, ID=250μA
Static Drain-to - Source On-resistance	RDS(ON)	0.4	Ω	VGS=10V, ID=5A
Continuous Drain current (in target package)	ID@25°C	10	A	VGS=10V
Continuous Drain current (in target package)	ID@100°C	6	A	VGS=10V
Operation Junction	Tj	-55~150	°C	
Storage Temperature	TSTR	-55~150	°C	

Target Device: IRF630

TO-220AB

Pd

100

W

@Tc=25°C

